

**Certificate of Analysis (CoA)**

Aug. 29, 2025

**Product Name:** Tin(II) Sulfide Sputtering Target**Chemical Formula:** SnS**Purity:** 99.9% (3N)**Dimensions:** Ø76.2 mm × 3.0 mm (±0.1 mm)**Backing Plate:** Elastomer bonded to OFHC Copper plate, 2 mm thick**Quantity:** 2 pcs**Lot Number:** CSJM-25SC-0830TB**Manufactured by:** Thin-Film Materials

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**Physical Description**

- Form: Ceramic/semiconducting sputtering target
- Appearance: Dark gray to black solid, dense surface
- Crystal Structure: Orthorhombic (SnS)
- Fabrication: Hot pressing, elastomer bonded to Cu plate
- Theoretical Density: ~5.22 g/cm<sup>3</sup>

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**Theoretical Stoichiometric Composition (Mass %)****Element Symbol Mass %**

Tin	Sn	~63.6%
Sulfur	S	~36.4%

*(Based on Sn = 118.71, S = 32.06, SnS = 150.77 g/mol)*

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**Chemical Composition (by ICP-OES / GDMS)**

Element	Symbol	Max. Content (ppm)
Tin	Sn	Balance (>99.9%)
Sulfur	S	Balance (>99.9%)
Iron	Fe	<20
Silicon	Si	<20

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Element	Symbol	Max. Content (ppm)
Calcium	Ca	<20
Other trace metals (each) –		<20
<b>Total Impurities</b>	–	<100 ppm

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**Handling & Storage**

- Store in vacuum-sealed packaging under inert atmosphere.
  - Handle carefully to avoid chipping or cracking.
  - Avoid prolonged exposure to air and humidity.
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**Declaration**

We certify that the above product has been manufactured and tested in accordance with our quality control system and meets the specifications stated herein.

**Authorized Signature:**Inspection Certificate by: Nancy LiuApprover by: Chen Qiang